

## Package: QFP

## < A tablie of contents >

| 1. Structure and materials   | 1/4 page        |
|------------------------------|-----------------|
| 2. Tape and Reel information | 1/4 to 3/4 page |
| 3. Storage conditions        | 3/4 page        |
| 4. Marking lot number        | 3/4 page        |
| 5. Footprint dimensions      | 3/4 page        |
| 6 Soldering conditions       | 3/4 to 4/4 page |

## 1.Structure and materials

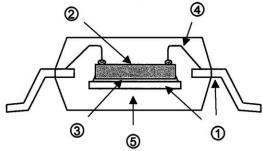


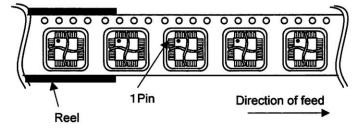
Fig. 1 Structure

| No. | Item       | Materials   |
|-----|------------|---|
| 1   | Lead Frame | Allpy 42 (External lead : Pb free solder plating) |
| 2   | Die        | Silicon   |
| 3   | Die Attach | Ag Paste  |
| 4   | Wire       | Au  |
| ⑤   | Molding    | Epoxy Resin                                       |

## 2. Tape and Reel information

## 2. 1. Packing specification

| Таре              | Embossed carrier tape(with dry pack) |
|-------------------|--------------------------------------|
| Quantity          | See the table on page 4/4            |
| Direction of feed | E2 (See Fig. 2)                      |



## 2. 2. Tape and Reel specification

2. 2. 1. Tape and reel dimensions ( See the table on page 4/4)

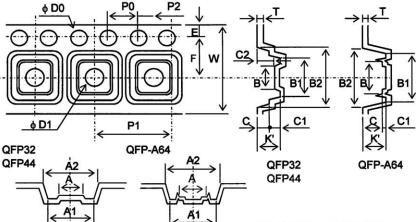


Fig. 3 Tape dimensions

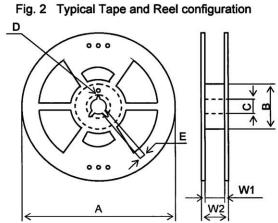


Fig. 4 Reel dimensions

#### 2. 3. Leader and Trailer

#### 2. 3. 1. Leader

No component pockets are 40 pockets or more.

#### 2. 3. 2. Trailer

No component pockets are 10 pockets or more. Tape is free from reel.

#### 2. 4. Label for Reel and Box

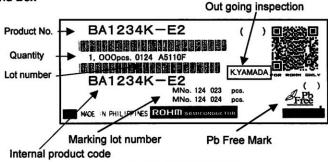


Fig. 5 Label example



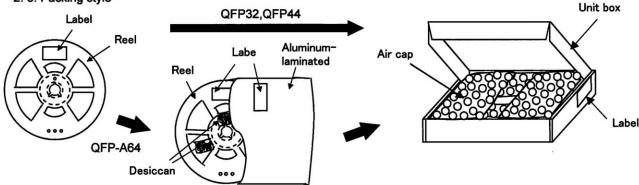
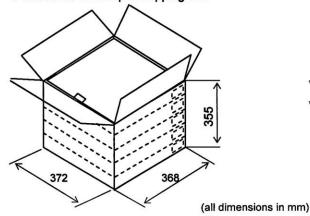


Fig. 6 Packing style

## 2. 6. Shipping style

5 unit boxes or less per shipping box



#### 2. 7. Packing materials

| Material            |  |  |  |  |
|---------------------|--|--|--|--|
| PS                  |  |  |  |  |
| PET + PE            |  |  |  |  |
| PS                  |  |  |  |  |
| Silicagel           |  |  |  |  |
| Aluminume-laminated |  |  |  |  |
| Polyethylene        |  |  |  |  |
| Cardboard           |  |  |  |  |
| Cardboard           |  |  |  |  |
|                     |  |  |  |  |

\*Please obey the indication of top side in a shipping box. \*1: QFP-A64

Fig. 7 Shipping box dimensions and Shipping style

#### 2. 8. Others

8. 1. Peelback strength Cover tape peelback strength is 0.2 to 0.7N.

Fig. 8 Test method



### 2. 8. 2. Missing Ics

- (1) No consecutive dropouts.
- (2) A maximun 0.1% of specified number of products in each packing may be missing.

## 3. Storage conditions

#### 3. 1. Storage environment

Recommended storage conditions are as follows:

-Temperature

: 5 to 30°C

-Humidity

: 40 to 70% RH

#### 3. 2. Storage period

-Specified storage period : 1 year

#### 3.3. Specified storage period until soldering

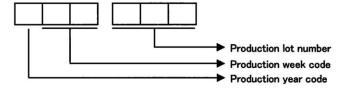
Regarding the dry packed packages, assemble package within 168hours, after dry pack is opened.

If the storage period has expired, the products must be baked 125°C for 24hours.

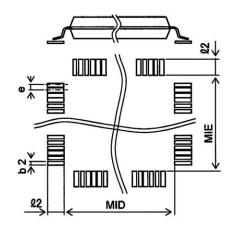
Maximum 2times baking for keeping solderbility.

Execute baking by 60°C/48hours while put in the embossed tape.

## 4. Marking lot number



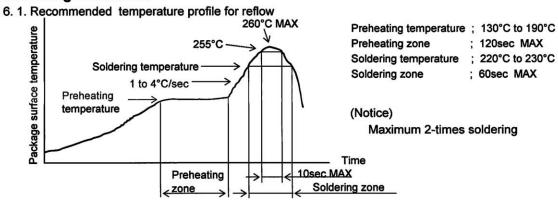
### 5. Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



(all dimensions in mm)

| Dookogo | Package Land pitch Land space e MID MIE |       | space | Land length | Land width |  |
|---------|---|-------|-------|-------------|------------|--|
| Package |   |       | ≥02   | b2          |            |  |
| QFP32   | 0.80                                    | 7.40  | 7.40  | 1.10        | 0.50       |  |
| QFP44   | 0.80                                    | 10.80 | 10.80 | 1.90        | 0.50       |  |
| QFP-A64 | 0.80                                    | 14.60 | 14.60 | 1.20        | 0.50       |  |

## 6. Soldering conditions



## 6. 2. Recommended condition for wave soldering

| Brasses    | Conditions     |           |  |  |  |  |
|------------|----------------|-----------|--|--|--|--|
| Process    | Temperature    | Time      |  |  |  |  |
| Preheating | 120°C to 150°C | 60sec MAX |  |  |  |  |
| Soldering  | 260°C ± 3°C    | 12sec MAX |  |  |  |  |

(Notice) Soldering time is provided for total soldering time in case of dual wave soldering.

#### 6. 2. 1. Notes for wave soldering

- (1) Do not use other soldering methods with wave soldering.
- (2) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (3) Optimize soldering condition to prevent solder bridging.

#### 6. 3. Recommended condition for solder iron

Recommended condition for solder iron
-Solder iron temperature : 380°C or less
-Mounting time : 4sec or less

#### < Tape dimensions >

| Dockogo   | Quantity | /    | Tape dimensions (all dimensions in mm) |      |      |        |       |            |     |      |            |            |
|-----------|----------|------|--|------|------|--------|-------|------------|-----|------|------------|------------|
| Package   | (pcs)    | Α    | A1                                     | A2   | В    | B1     | B2    | С          | C1  | C2   | D0         | D1         |
| QFP32     | 1500     | 6.0  | 9.5                                    | 9.8  | 6.0  | 9.5    | 10.8  | 0.8        | 1.4 | 1.7  | φ1.5       | φ1.6       |
| QFP44     | 1000     | 9.0  | 14.45                                  | 14.9 | 9.0  | 14.5   | 14.9  | ) <u> </u> | _   | 2.2  | φ1.5       | ф2.0       |
| QFP-A64   | 500      | 13.3 | 17.4                                   | 17.8 | 13.3 | 5 17.4 | 17.8  | 2.8        | 1.5 | -    | φ1.5       | ф2.0       |
| Tolera    | nce      | _    | ±0.1                                   | ±0.1 | _    | ±0.1   | ±0.1  | -          | -   | ±0.1 | +0.1<br>-0 | +0.1<br>-0 |
| Deekees   |          | Тар  | Tape dimensions (all dimensions in mm) |      |      |        |       |            |     |      |            |            |
| Package   | E        | F    | K'                                     | P0   | P1   | P2     | Т     | W          |     |      |            |            |
| QFP32     | 1.75     | 7.5  | 2.2                                    | 4.0  | 12.0 | 2.0    | 0.3   | 16.0       |     |      |            |            |
| QFP44     | 1.75     | 11.5 | 2.4                                    | 4.0  | 16.0 | 2.0    | 0.3   | 24.0       |     |      |            |            |
| QFP-A64   | 1.75     | 11.5 | 3.3                                    | 4.0  | 24.0 | 2.0    | 0.3   | 24.0       |     |      |            |            |
| Tolerance | ±0.1     | ±0.1 | ±0.1                                   | ±0.1 | ±0.1 | ±0.1   | ±0.05 | ±0.3       |     |      |            |            |

## < Reel dimensions >

| Package   | Reel dimensions (all dimensions in mm) |      |       |       |     |      |      |  |
|-----------|--|------|-------|-------|-----|------|------|--|
|           | Α                                      | В    | С     | D     | E   | W1   | W2   |  |
| QFP32     | ф330                                   | ф80  | ф13.0 | φ20.2 | 1.5 | 17.5 | 22.5 |  |
| QFP44     | ф330                                   | φ100 | ф13.0 | φ20.2 | 1.5 | 25.5 | 30.5 |  |
| QFP-A64   | ф330                                   | φ100 | φ13.0 | ф20.2 | 1.5 | 25.5 | 30.5 |  |
| Tolerance | _                                      | _    | ±0.2  | MIN   | MIN | ±1.0 | MAX  |  |

< Dehydrated weight >

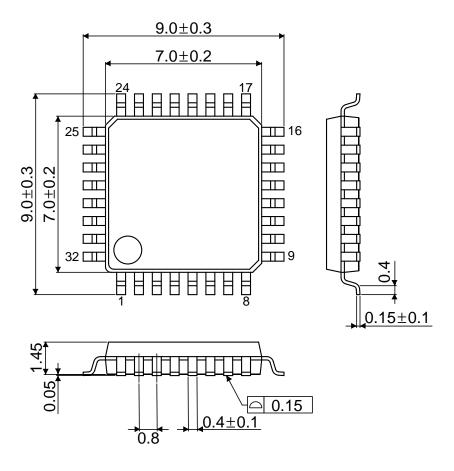
| Dehydrated weight dimensions in g |
|-----------------------------------|
| 0.20                              |
| 0.57                              |
| 1.23                              |

4/4



# Package Dimensions

## QFP32

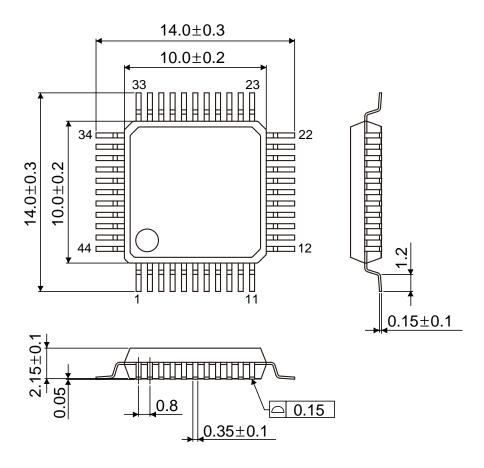


(Unit: mm)



# Package Dimensions

## QFP44

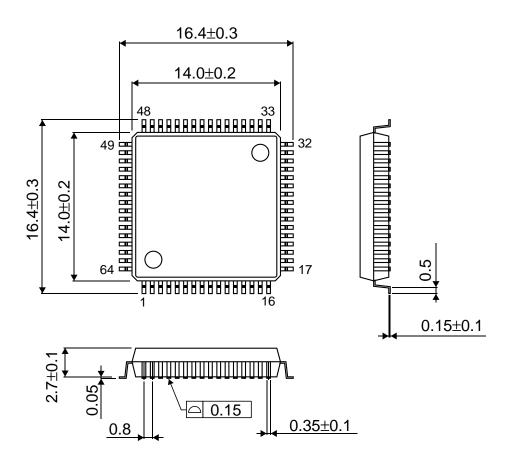


(Unit: mm)



# Package Dimensions

QFP-A64



(Unit: mm)

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